

ABSTRACT

A retaining ring to be fitted on a chemical mechanical polishing apparatus for semiconductor wafers is disclosed, the retaining ring being of integral design made of a plastic material, wherein the retaining ring forms on a first front side thereof a bearing surface for supporting the retaining ring on a polishing surface of the polishing apparatus, and includes on the side thereof lying opposite the first front side thereof in axial direction fitting elements for fitting the retaining ring on the polishing apparatus.

403033app